

IN THE  
**United States Patent and Trademark Office**

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<b>Applicant(s):</b> Kazumitsu Seki, et al.	<b>Docket No.:</b> 17314-018
<b>Serial No.:</b> 10/599,661	<b>Art Unit:</b> 4116
<b>Filed:</b> October 4, 2006	<b>Examiner:</b> Chen, Yu
<b>For:</b> Palladium-Plated Lead Finishing Structure For Semiconductor Part And Method Of Producing Semiconductor Device	

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Mailstop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT AND RESPONSE**

Further to the Non-Final Office Action dated February 26, 2009 (hereinafter "Office Action"), in view of the following amendments and/or remarks, Applicants request entry thereof and reconsideration of the above-referenced application.

**Amendments to the Drawings** are discussed beginning on page 2 and are included as a Replacement Sheet in Attachment A.

**Amendments to the Claims** are included starting on page 3.

A **Remarks** section is included starting on page 5.